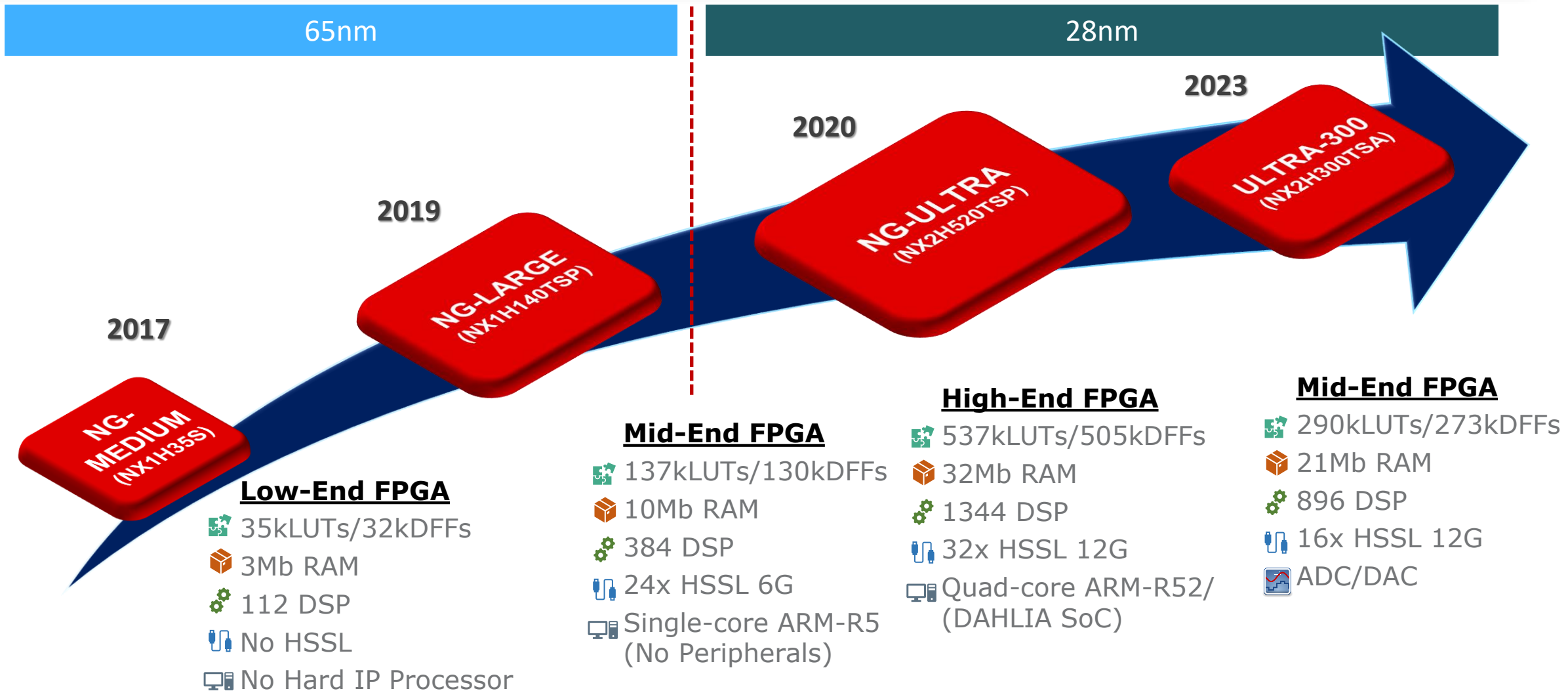


BRAVE Days Company Update

2023

Rad-Hard SoC FPGA Current Portfolio



Current NX FPGA Positioning in Space

Best platform offering

➤ Structures

➤ Power

➤ Thermal Control

➤ Attitude Control

➤ Guidance

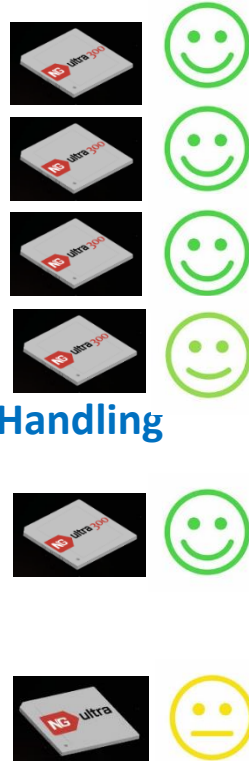
➤ Command and Data Handling

➤ Propulsion

➤ Harness

➤ Payload

➤ Life Support



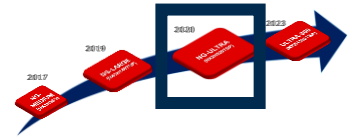
Examples:

- On Board Computer
- Mass memory
- Remote Terminal Units
- Data interfaces
- etc ...

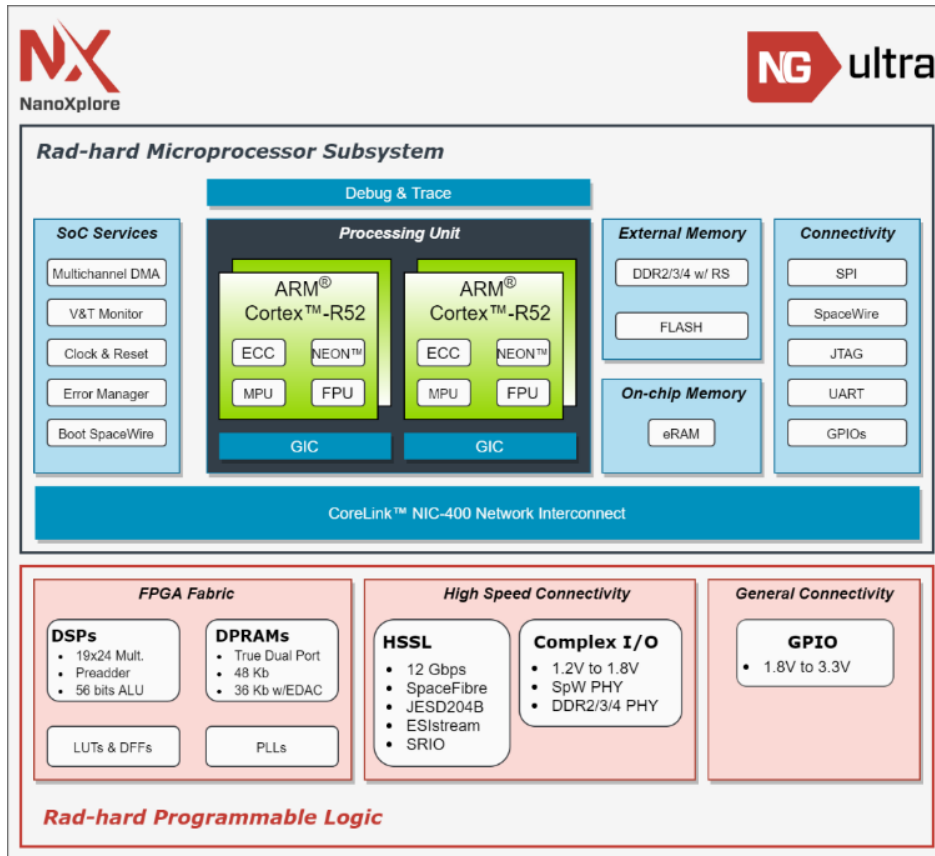




NG-ULTRA

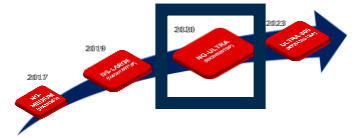


- Ongoing qualification
- First PFM delivered
- Evaluation kit and prototypes leadtime significantly reduced
- Supply chain up and running at full speed





NG-ULTRA FM Package



NanoXplore

SPCNGFPU-PKUBAE

NX3H5A - F1760E

VQ242953

33 2334A

FRA

1




NG-ULTRA Qualification Strategy

Address Class 1 down to New Space

	NG-ULTRA COTS	NG-ULTRA ESCC9030
Mission profile	Life Time duration 7 years @85°C Tj 30 krad	Life Time duration 18 years @85C Tj (GEO1) 50 krad Life Time duration 16 years @105C Tj (GEO2) 25 krad
Die	28FD-SOI GEO	
Package	45x45 TEFBGA non hermetic	
Solder balls	Lead free - SACN306	SnPb
Capacitors embedded in package	General purpose capacitors	Space grade capacitor
Visual die sorting	NO	YES
Precap	NO	YES
Marking ID Serialization	YES	YES
Thermal cycling	NO	YES
SAM	Standard Control Plan	ESCC9030 Control Plan
XRAY and VI post-assy	NO	YES
Qualification referential	JEDEC	ESCC9030
Qualification maintenance	NO	YES (as defined in ESCC9030)
Screening for customer parts	EWS ambient – FT hot T°	ESCC9030 EWS ambient + FT 3T/BI/3T
VI before shipment to customer	Automatic Optical VI	External VI + CoC
Datapack	NO	YES


Radiation test sessions overview

NG-ULTRA FPGA Radiation test campaigns overview

- 2019
- 
- UCLouvain / HIF (BE)

DEMETER
Test chips

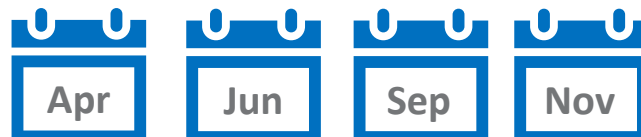


- 2020 2021
- 
- UCLouvain / HIF (BE)

NG-ULTRA V1
1st prototypes



Parts thickness: 50, 70 μ m
Tilt and roll possible

- 2023 2023 2023 2023
- 
- RADEF Jyväskylä (FI)

NG-ULTRA V2
final



Parts thickness: 100 μ m
Tilt and roll not possible
or high energies

Radiation test next steps

⚛️ +1 more HI test session planned Q2 2024 at RADEF Jyväskylä (FI)

⚛️ +1 HI sessions planned dedicated to the SoC in 2023 at RADEF Jyväskylä (FI)

⚛️ +1 Proton test sessions being planned at PSI in 2024

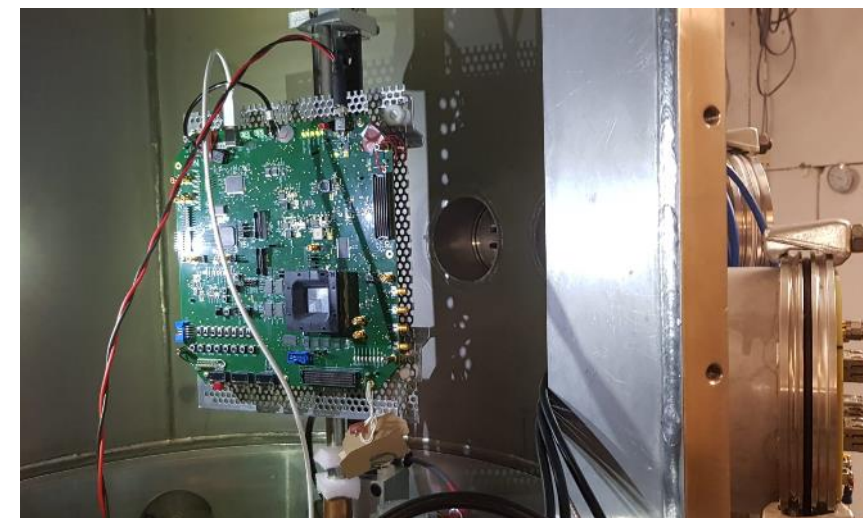
✓ **Radiation performances characterized so far are extremely strong !**

Summary of the Configuration Memory (CMEM) test

- Test campaign: RADEF April-2023
- Number of bit in the configuration memory: **90.834.656**
- Bits Location: distributed in the whole chip
- Test Configuration:
 - Bitstream with Checkerboard (0101.....01)
 - CMIC (internal scrubber) : disabled
 - Voltage VDD_CORE -5% // nominal,
 - runs of 200 sec (shutter controlled, closed during configuration and readback)
- Number of samples: 3
- Flux: 5K ions/cm²/s
- Fluence reached : 1E+07 ions/cm²

0 errors in CMEM up to LET 62 MeV*cm²

✓ Result consistent with the previous radiation test campaigns.

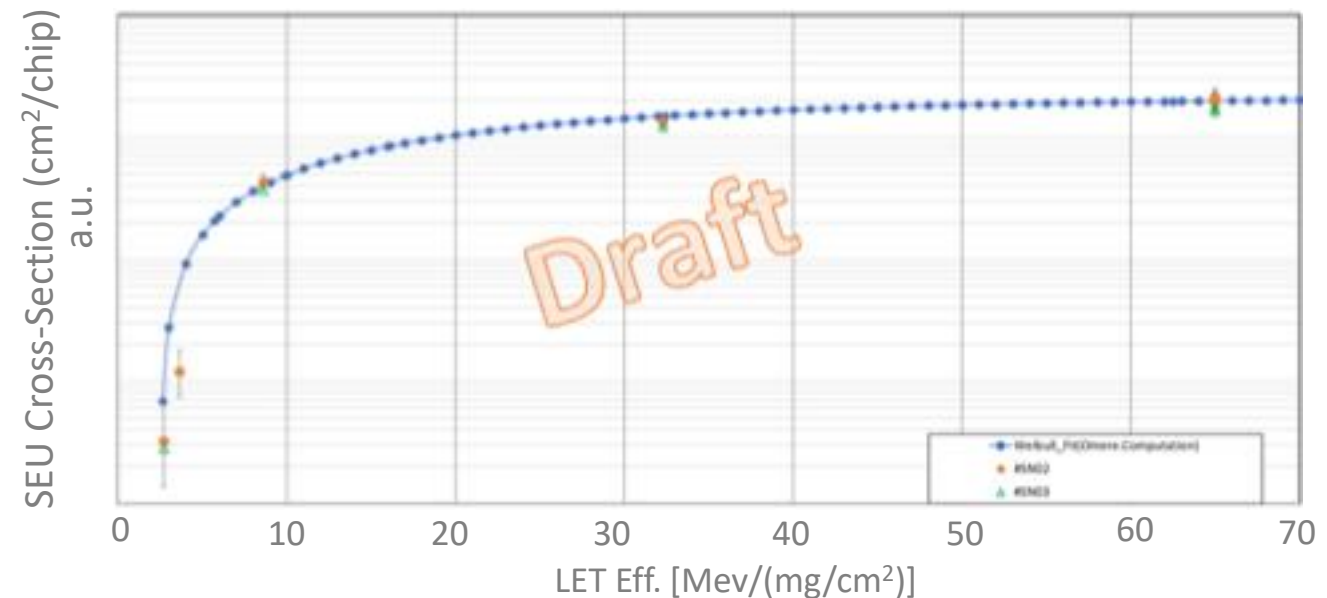


Summary of the DPRAM test


- Test campaign: RADEF April-2023
- Number of instances: **88 (672) 12% 4325376 bits**
- Location: 2 rows of each lobe (6 / 5)
- Test Configuration:
 - **Bitstream1** : NOECC_2k x 24
 - **Bitstream2** : FAST_2k x 18
 - Voltage VDD_CORE -5% // nominal
- Number of samples: 2
- Flux: up to 15K ions/cm²/s for bitstream2
- Fluence reached : 1E+07 ions/cm²

**No errors were detected using the ECC
(even under flux : 15K ions/cm²/s)**

 **Bitstream1** : NOECC_2k x 24 [3 runs]



✓ Results without ECC consistent with ST radiation data

 **Bitstream2** : FAST_2k x 18 [11 runs with **ECC enable**,
0 run returned error (count by ECC activation)]

Summary of the DFF tests

- Test campaign: RADEF April-2023
- Number of instances: **15k DFF (4%)**
- Bits Location: Lobe R3
- Test Configuration:
 - Bitstream : 15k stages, Window Shift Register (**WSR**)
 - Design frequency: 50 MHz / 80 MHz
 - Voltage VDD_CORE -5% // nominal,
- Number of samples: 2
- Flux: 10K ions/cm²/s
- Fluence reached : 1E+07 ions/cm²

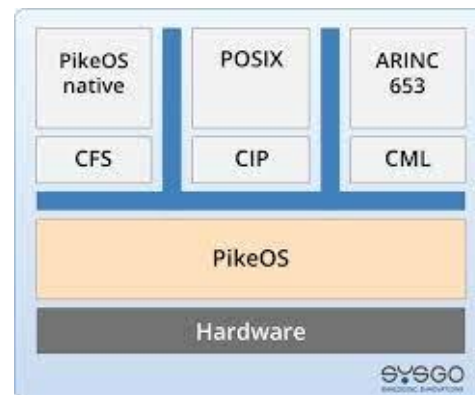
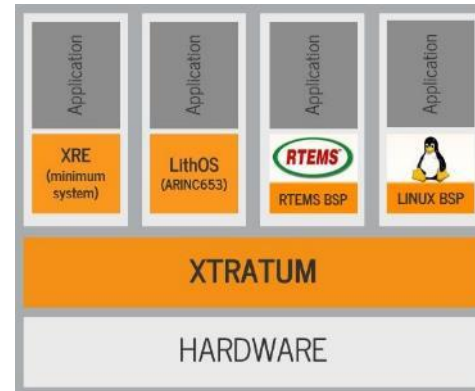
**0 errors detected during the campaign
(up to LET 62 MeV*cm² /mg)**





OS Supports

Complete ecosystem

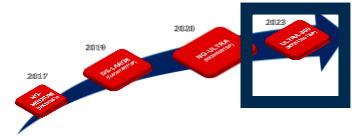




ULTRA300

Device		Details	NX2H300TSA
Capacity - ASIC Gates			4 000 000
Logic Modules	Rad Hard FPGA	11x Tiles + 7CGBs	
Register		384DFF on 11rows	273 408
LUT-4		408LUT on 11rows	290 496
Carry		96CY on 11rows	68 352
Embedded RAM			22Mb
DPRAM	Rad Hard SOC	448BRAM * 48Kb	21 504
Core Register File		On 11 rows	1 424
Core Register File Bits		32*18bits	807K Hardened
Clocks / PLL			50 / 6
Additional Features	Rad Hard SOC		
SpaceWire PHY (8 IOBs)		2x/Complex IOBank	20
DDR3/4 PHY (11IOBs)		2x/Complex IOBank	20
DSP Blocks		From 7 rows	896
SpaceWire link I/F 430Mbps		CODEC	1
SERDES Tx/Rx 12,5Gbps (supporting several protocols such as Space Fibre)		4 Quad HSSL 12,5Gbps	16
Hard IP Processor core / SoC			NO
ADC		12-bit ADC, 10Msps	1
DAC		13-bit DAC, 10Msps	1
Design Security			YES
Inputs / Outputs	I/O		547 I/Os
Complex I/O bank		VIO 1,2 – 1,5 – 1,8V	10 x 34 I/Os
Simple I/O bank		VIO 1,8 – 2,5 – 3,3V	6 x 24 I/Os + 1 x 16 I/Os
Packages - User I/Os	PKG		
FF484 organic		27*27 mm / 1 mm	239 I/Os (TBC)
FF1152 organic		35*35 mm / 1 mm	547 I/Os (TBC)

- 290 KLUT density
- 16 HSSL @ 12 Gbps
- ADC & DAC
- 13—bit DAC, 1-10 MSPS
- 12—bit ADC, 1-10 MSPS up to 8 inputs
- Small footprint in BGA 484





ULTRA 300 Update



- First engineering samples received
- Same supply chain as NG-ULTRA
- Same qualification approach for Class 1 and New Space
- Enhanced security features by end 2024
- Leadtime
 - Eval kit Q2 2024
 - Prototypes Q1 2024
 - PFM Q1 2025

⚛️ 2 HI test session planned in 2024 at RADEF Jyväskylä (FI)

⚛️ +1 Proton test sessions being planned at PSI in 2024

✓ **Same blocks as NG-ULTRA -> should have the same radiation performance**



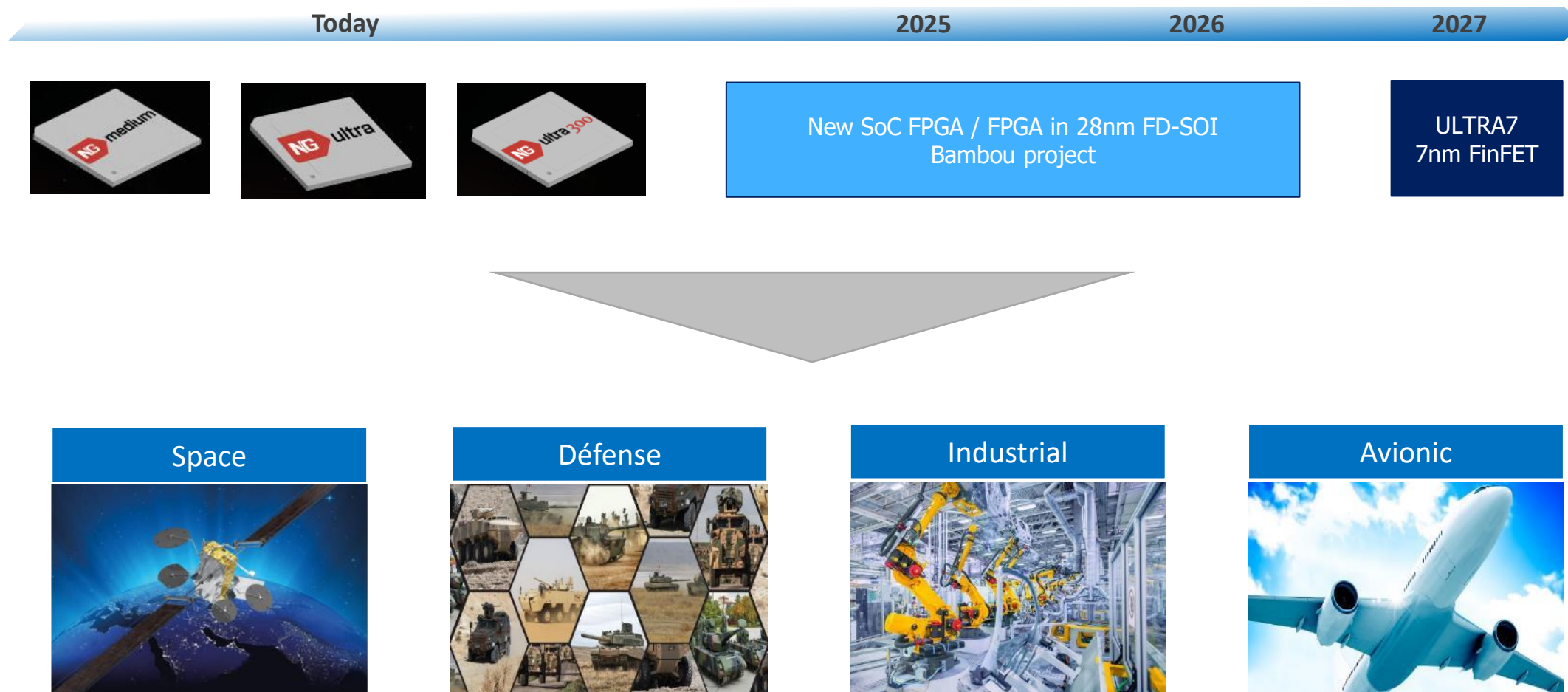
Next?

4 Year Roadmap to solve Space Equation



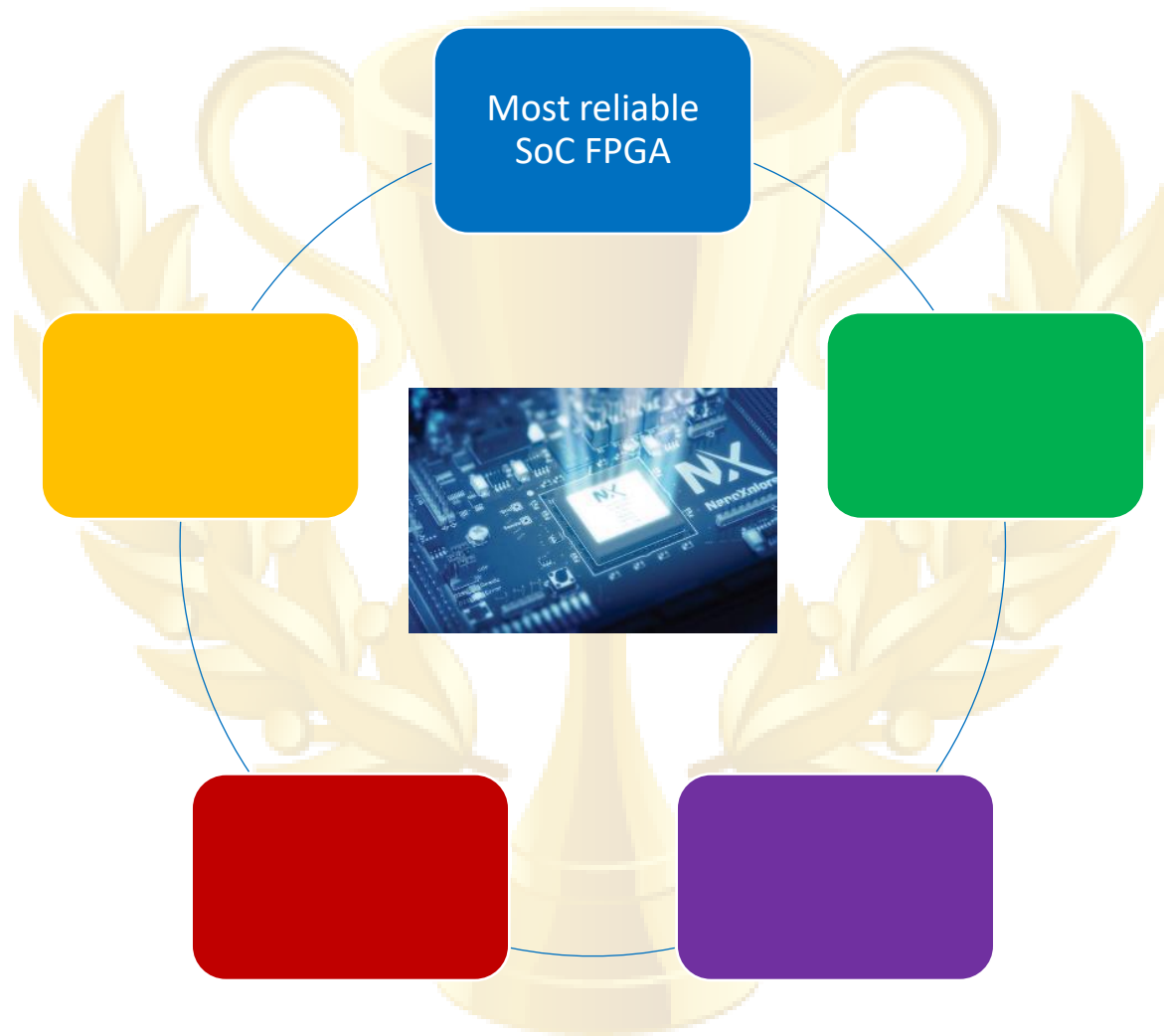
4 Years Roadmap Summary

Clear roadmap to address strategic markets with our differentiators



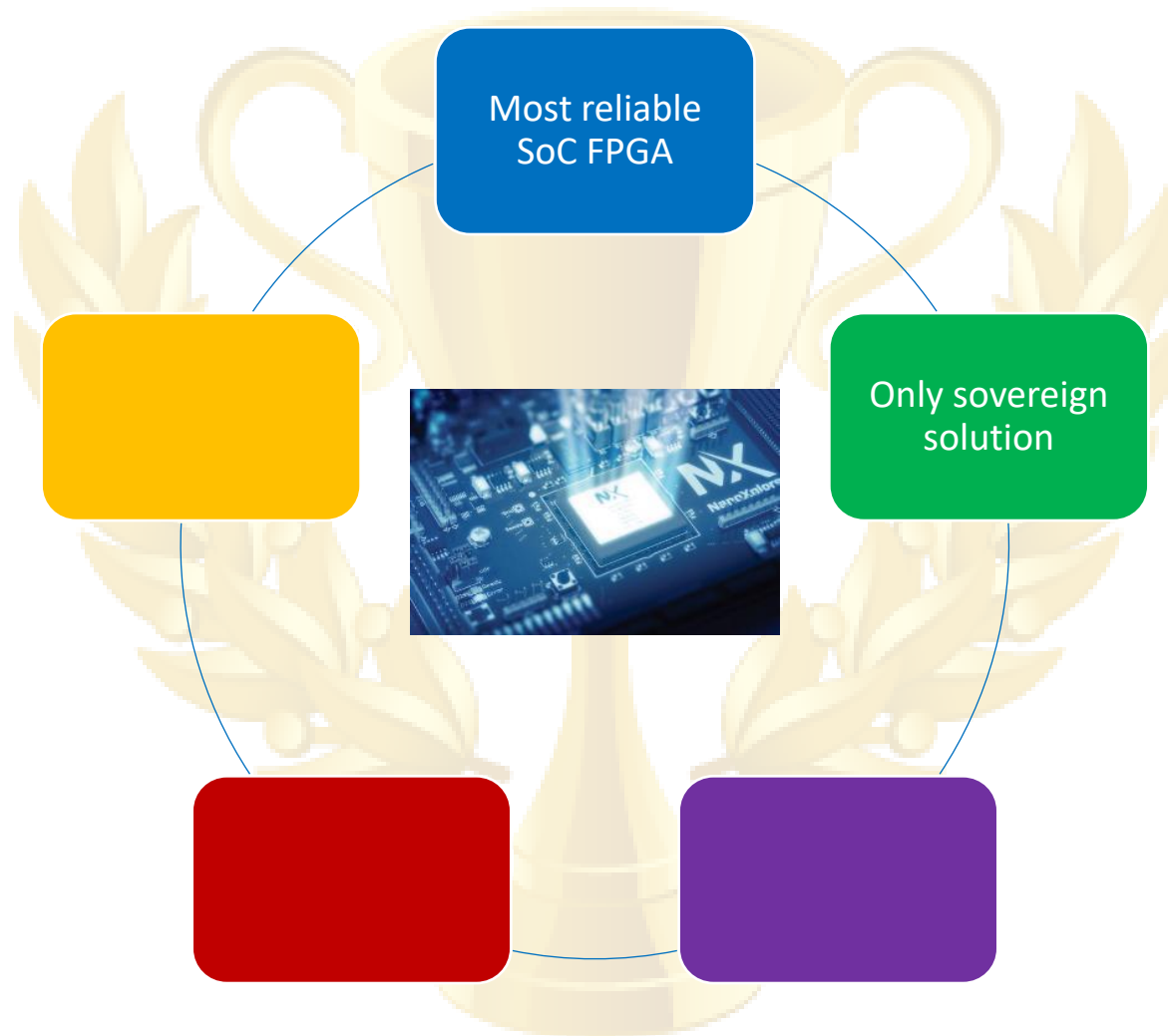
NX Key Differentiators

Key technologies differentiators for the only sovereign offering



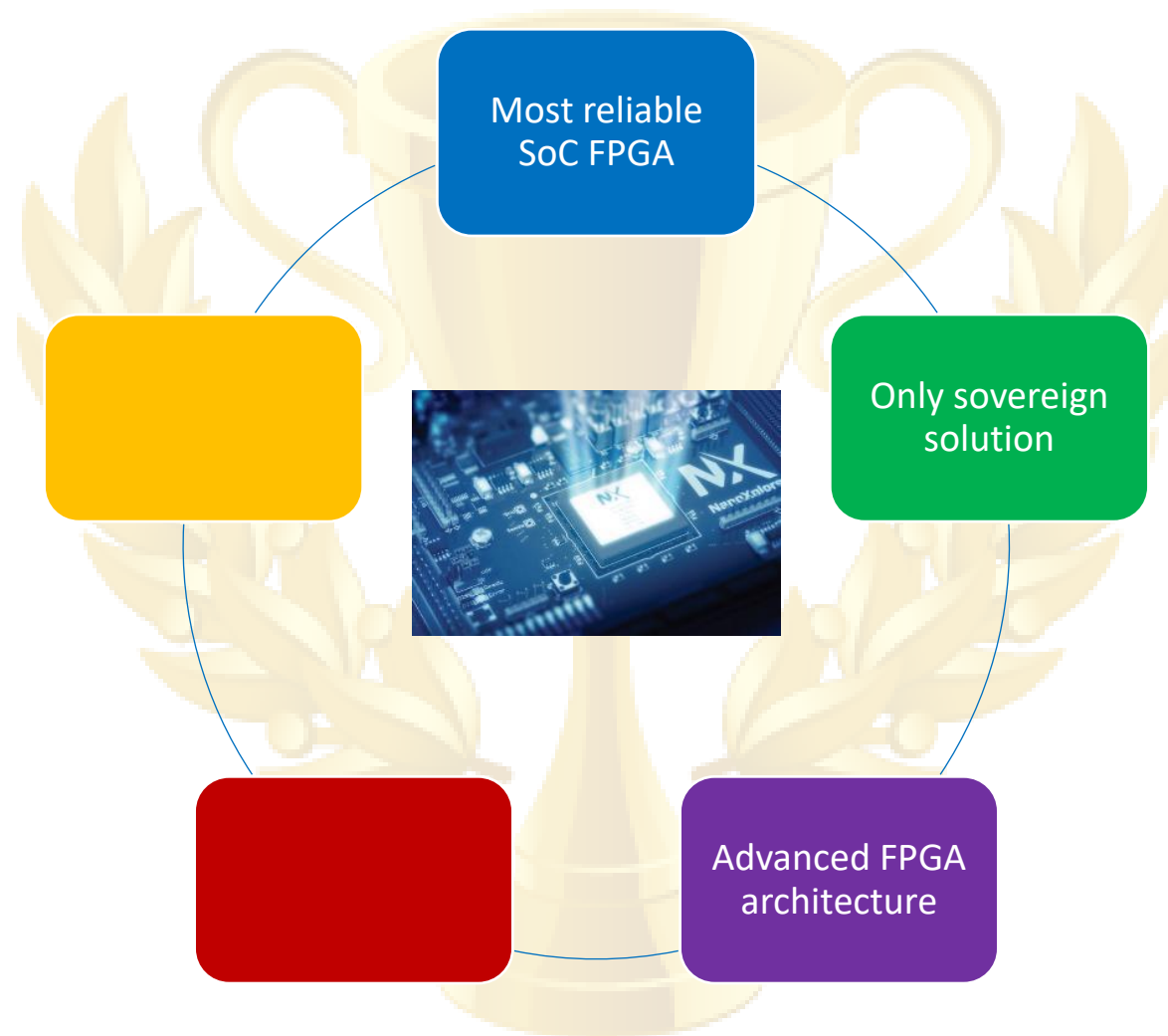
NX Key Differentiators

Key technologies differentiators for the only sovereign offering



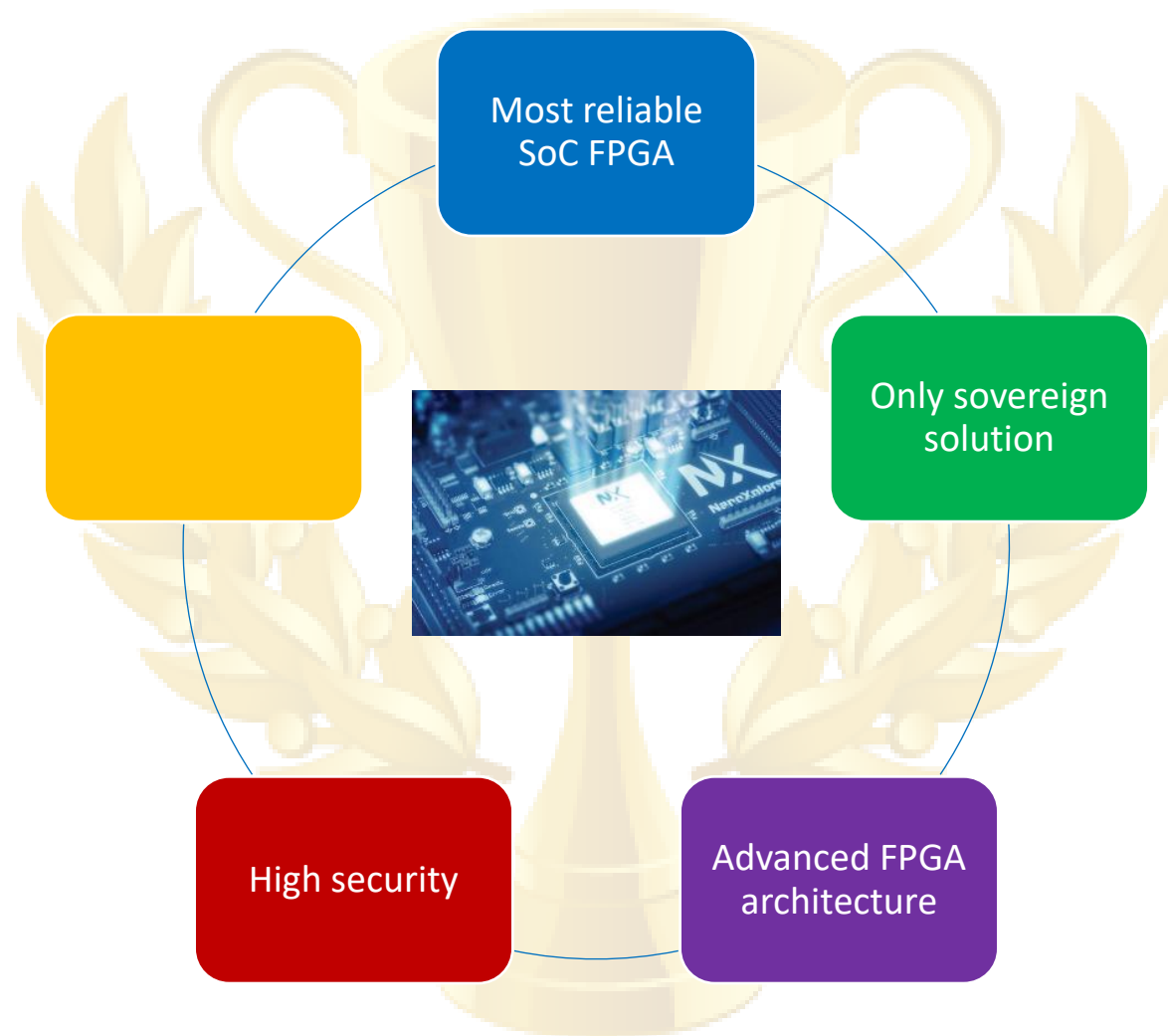
NX Key Differentiators

Key technologies differentiators for the only sovereign offering



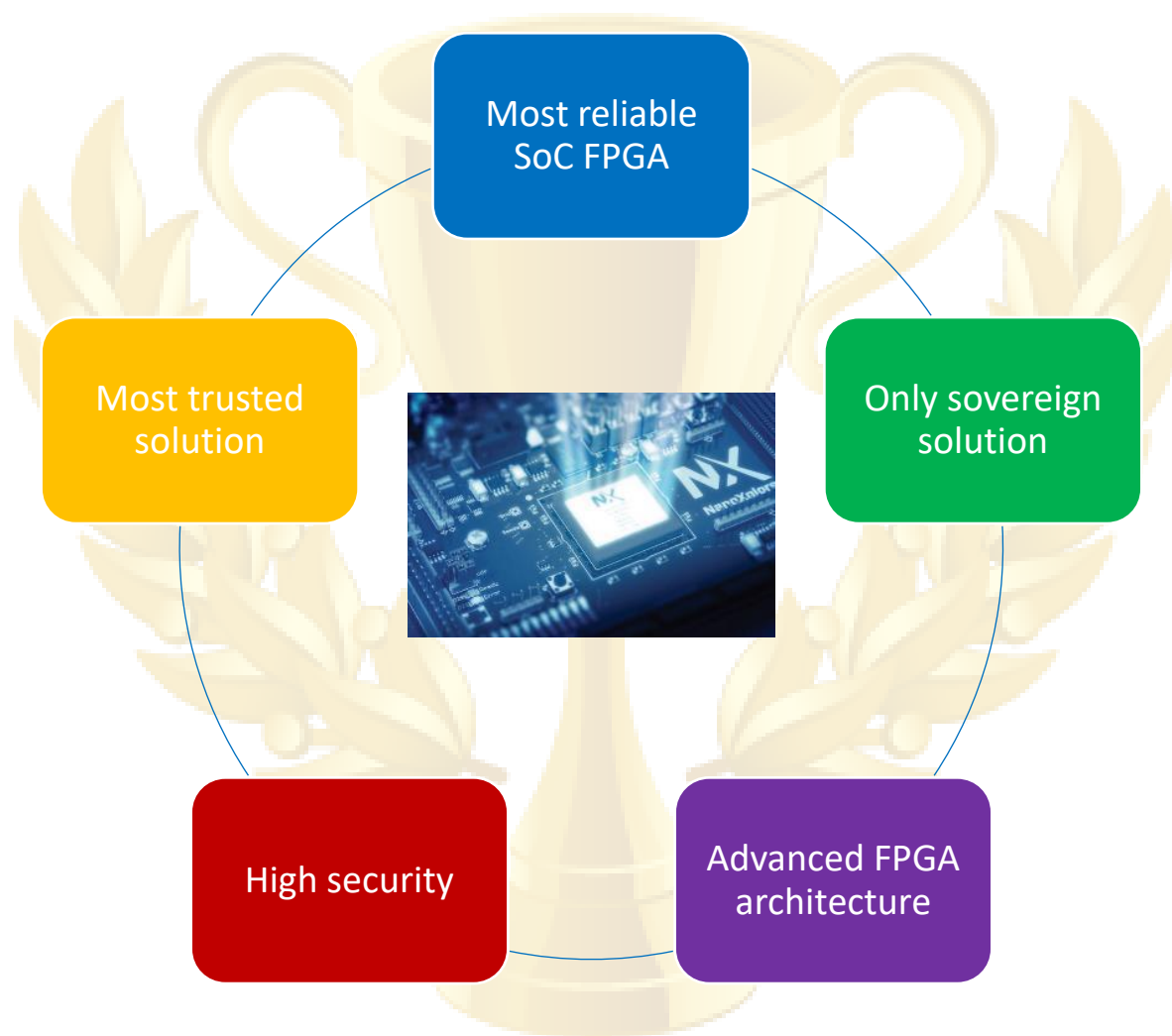
NX Key Differentiators

Key technologies differentiators for the only sovereign offering



NX Key Differentiators

Key technologies differentiators for the only sovereign offering



IMPULSE Roadmap

